

Abstract

The present invention provides electrodeposited copper foil with carrier which has an organic adhesive interface layer permitting control of the lower limit of peel strength
5 between a carrier foil and an electrodeposited copper foil and to a method for producing the electrodeposited copper foil with carrier. In the electrodeposited copper foil with carrier including a carrier foil, an adhesive interface layer formed on the carrier foil, and an electrodeposited copper
10 foil formed on the adhesive interface layer, the carrier foil is formed of a copper foil and the adhesive interface layer contains an organic agent and metallic particles, the organic agent and the metallic particles being in an intermingled state.